INPULSETM 2kW Pulsed Power Modules for Advanced Magnetron Sputtering



Kurt J. Lesker Company PROCESS EQUIPMENT

Applications

- High-Power Impulse Magnetron Sputtering
- High-Power Pulsed Magnetron Sputtering (HiPIMS/HPPMS)
- Advanced coatings for university, industrial and governmental R&D applications
- Dense, high-hardness materials, non-porous films and superior optical coatings
- Ideal for 2", 3" and 4" circular magnetrons requiring high impulse power and pulse flexibility

Features

- Up to 200 A peak current capability for power handling and high deposition rate
- User selectable pulse width, frequency and peak current
- Real-time discharge voltage and current monitoring; integrated power feedback with touch-screen control
- · Arc detection and suppression technology
- Precision master/slave module timing for substrate bias or cathode synchronization for co-deposition

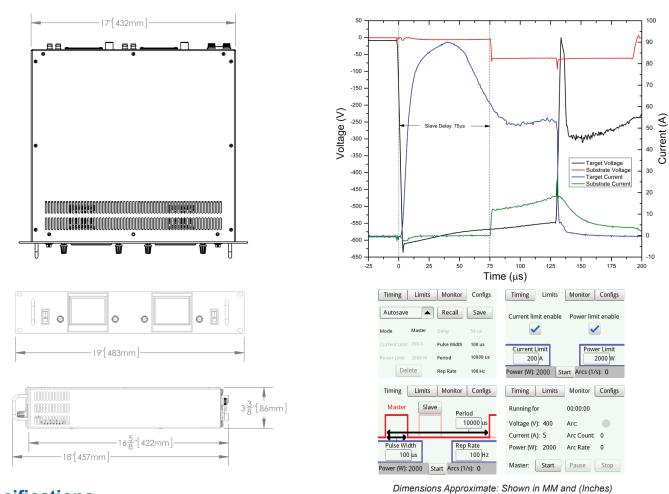
Process

- Easy way to upgrade existing DC sputtering systems for HiPIMS/HPPMS and reactive capability
- Use your existing DC power supply as the charging supply or bias input*

Options

- Available in single or dual module configuration in standard 2U rack enclosure to power multiple magnetron heads, i.e. cluster tools, or a pulsed substrate bias with sub µs timing
- Touch screen interface with direct parameter entry and tactile knob control, plus rear panel RJ-45 microcontroller interface with external TTL sync pulse and monitor outputs
- Pair with upgraded magnetic pack for higher performance TORUS[®] PVD tools

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Specifications

Input Power Specifications 1 phase, 100-240 VAC, 50/60 Hz, <1 A per 1000 VDC nominal, 1250 VDC tolerant Input Charging Supply Time-Average Power Up to 2 kW Output Peak Voltage 1000 V nominal, 1250 V tolerant **Output Peak Current** 200 A max Arc Detection Time <1 µs Peak Current Limiter User selectable, up to 200 A Power Limit Mode User selectable, up to 2 kW **Pulse Frequency** User selectable, 0.1 kHz to 10 kHz nominal range Pulse Width User selectable, 5 µs to 1 ms nominal range RJ-45 control I/O, BNC sync line, BNC I-V monitor out **External Communications** Pulse Module Sync <0.1 µs latency Cabling N-type HV connector standard, other options available **Configuration Storage** Onboard storage for 5 user selectable presets **Physical Dimensions** 2U rack (19" wide); 86 mm (H) x 483 mm (W) x 457 mm (L) with handles 3.25 kg for single module, 4.65 kg for dual module Weight Operating Temperature +5C to +40C, Forced Air Cooling

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